

Wet Etching Agent for Semiconductors with Surfactant Buffered Hydrofluoric Acid BHF-U Series

 TECHNICAL
DATASHEET

The wet etching agents in the Buffered Hydrofluoric Acid BHF-U Series are agents that are a mixture of hydrofluoric acid and ammonium fluoride to which we have added surfactant.

Introduction

- Buffered Hydrofluoric Acid with Surfactant BHF-U Series are high quality etching agents in which the level of impurities, such as metal ions, have been greatly decreased for use in semiconductor manufacturing.
- Like the BHF series, the etching rate and selectivity can be controlled by the mixing ratio of hydrofluoric acid and ammonium fluoride.
- Addition of surfactant improves wettability, suppresses Poly-Si etching, reduces particle adhesion on the wafer, and prevents Si surface roughness.

General physical properties

Items	Unit	Numeric Value
HF Concentration	mass%	Varies by mixture ratio
NH4F Concentration	mass%	

Inspection Items

- Anionic impurities(Cl, NO₃, PO₄, SO₄)
- Metal impurities(Fe, Na, K, etc., more than 20 metals)
- Particles

Please contact us for details on the quality levels of individual items.

Handling method/Safety information

- Be sure to read the notes on SDS and labels before use.
- This product has been developed for industrial purposes and we shall not guarantee the safety if used for any other purposes. If it is going to be used for medical or food applications, please contact us in advance.

Packing specification

- 22.5L bottle, 200L drum

For more information, visit our website.

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